

NOTES : UNLESS OTHERWISE SPECIFIED

1.

SCHEMATIC DIAGRAM FOR THIS PRODUCT IS 870012505-X00.
2.

ELECTRICAL COMPONENTS ARE IDENTIFIED BY REFERENCE DESIGNATOR ON ASSEMBLY DRAWING, BILL OF MATERIALS, AND SCHEMATIC DIAGRAM.
3.

APPLICABLE BILL(S) OF MATERIAL FOR THIS ASSEMBLY DRAWING: 980012505-X00.
4.

SOLDER PASTE GERBER PATTERN 881012505-00X MAY BE MODIFIED PER ASSEMBLY REQUIREMENTS.
5.

DENOTES ORIGIN 0x AND 0y FOR COMPONENT POSITIONS PER PLACE.TXT FILE.
6.

FID1 THRU FID6 ARE THE OPTICAL ALIGNMENT TARGETS FOR SURFACE MOUNTED COMPONENTS. FOR 0x AND 0y LOCATION REFER TO THE PLACE.TXT FILE.
7.


ALL VENDOR IN-PROCESS MARKING, QA STAMPS, ETC., MUST BE PLACED ON THE BOTTOM SIDE OF BOARD.
8.

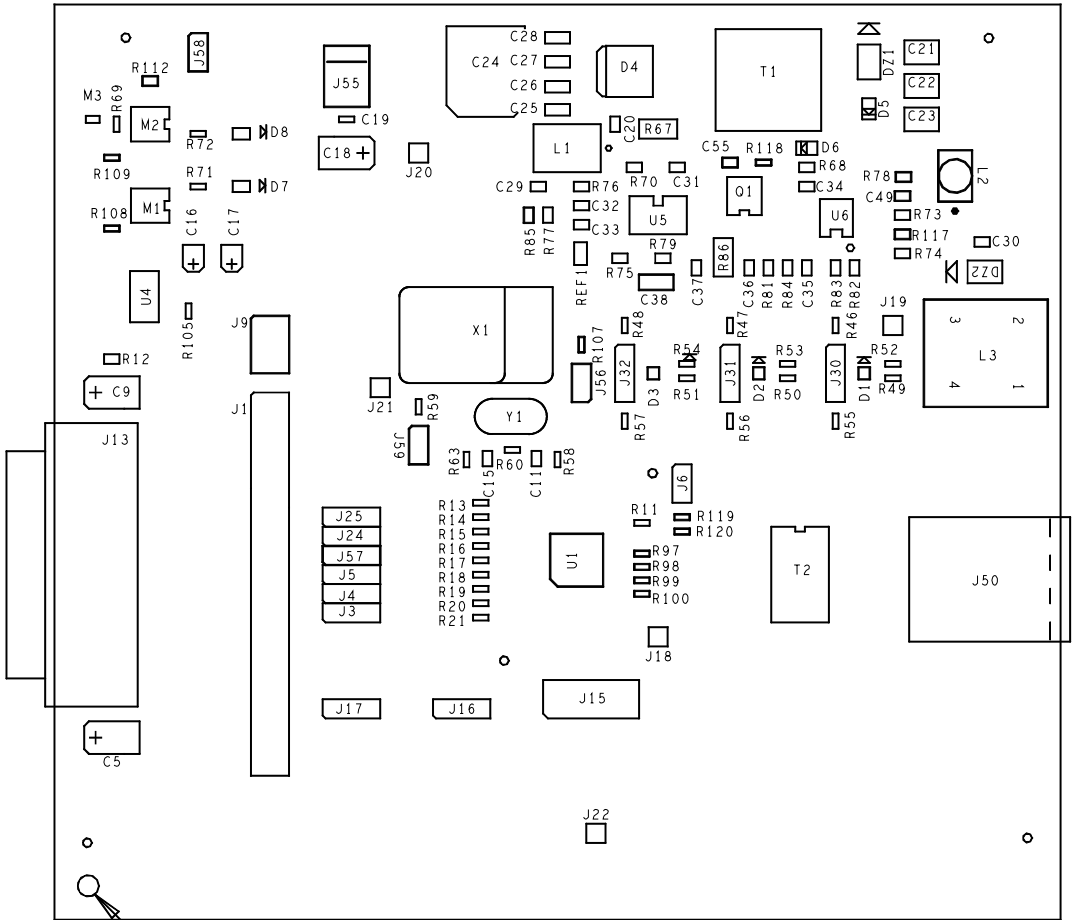
EACH ASSEMBLED BOARD MUST BE PACKAGED IN AN ESD BAG AND SEALED WITH AN ESD LABEL.

REVISIONS			
REV	DESCRIPTION	APPRVD	DATE
A	INITIAL RELEASE		2-8-05

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DO NOT SCALE DRAWING		<div> National Semiconductor COMMUNICATIONS INTERFACE</div>	
SIGNATURES	DATE		
DRAWN BY: BILL LANDUCCI	2-8-05		
CHECKED BY:			
APPRVD BY:		PCB ASSEMBLY DRAWING DP83848 AspenPHY DEMO II	
APPRVD BY:		B	DWG 980012505-000 A
		SCALE: NONE	SHEET 1 OF 3 REV



VIEWED FROM TOP SIDE

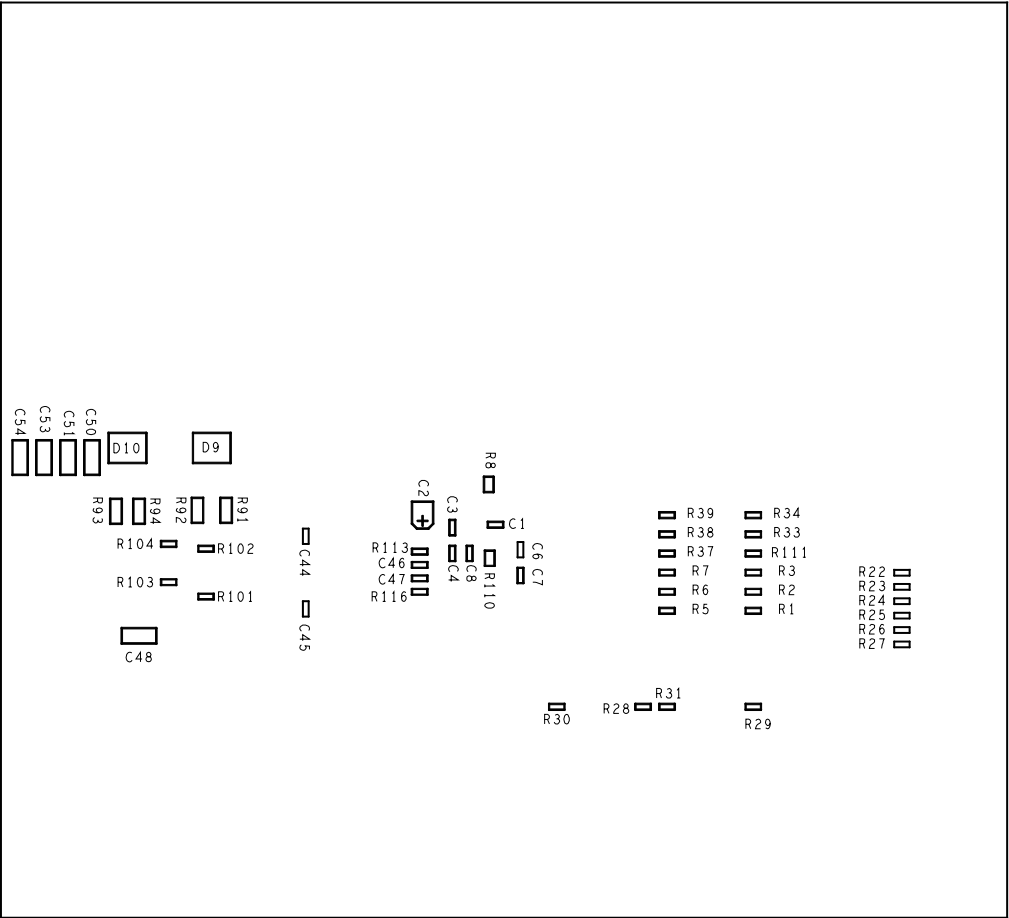
5



PCB ASSEMBLY DRAWING
DP83848 AspenPHY DEMO II

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VIEW FROM BOTTOM SIDE



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DP83848 AspenPHY DEMO II

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SCALE: NONE	SHEET 3 OF 3	REV